

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A quartz ring for use in a plasma processing apparatus, comprising:

an inner perimeter;

a main surface extending outwardly from the inner perimeter;

a first portion around the inner perimeter, the first portion having a flat first region on the main surface and being in direct contact with plasma; and

a second portion adjacent to an outer perimeter of the first portion having a smaller thickness than that of the first portion, the second portion having a second region adjacent to the first region on the main surface, the second region having a height lower than that of the first region, the second portion extending outwardly from the outer perimeter of the first portion to ~~the~~ an outer perimeter of the quartz ring;

wherein the first region and the second region are regions of the quartz ring and are parallel to each other, wherein the first portion and the second portion are of a monolithic piece of the quartz ring, and wherein the quartz ring surrounds a wafer holder.

2. (Previously Presented) The quartz ring according to claim 1, wherein the second region is flat and is parallel to the first region.

3. (Previously Presented) The quartz ring according to claim 1, further comprising a flat second surface opposite to the main surface, the second surface being parallel to the first region.

4. (Previously Presented) The quartz ring according to claim 1, wherein a difference of the heights of the first region and the second region is about 0.1 mm to about 2 mm.

5. (Previously Presented) The quartz ring according to claim 1, further comprising a second surface opposite to the main surface, the second surface having a beveled portion along the inner perimeter.

6. (Currently Amended) A plasma processing apparatus, comprising:
a processing chamber to accommodate a workpiece to be processed;
an electrode within the processing chamber to generate a plasma, the electrode having an outer perimeter; and
a quartz ring that surrounds the outer perimeter of the electrode, comprising:
an inner perimeter;
a main surface extending outwardly from the inner perimeter;
a first portion around the inner perimeter, the first portion having a flat first region on the main surface and being in direct contact with plasma; and
a second portion adjacent to an outer perimeter of the first portion having a smaller thickness than that of the first portion, the second portion having a second region adjacent to the first region on the main surface, the second region having a height lower than that of the first region extending outwardly from the outer perimeter of the first portion to the outer perimeter of the quartz ring;
wherein the first region and the second region are regions of the quartz ring and are parallel to each other, wherein the first portion and the second portion are of a monolithic piece of the quartz ring, and wherein the quartz ring surrounds a wafer holder.

7. (Previously Presented) The apparatus according to claim 6, wherein:
the outer perimeter of the electrode has a side surface; and
the inner perimeter of the quartz ring has a side surface that faces the side surface of the outer perimeter of the electrode.
8. (Previously Presented) The apparatus according to claim 6, wherein:
the workpiece to be processed is mounted on the electrode; and
a height of the first region of the quartz ring is substantially the same as that of a surface of the workpiece mounted on the electrode.
9. (Previously Presented) The apparatus according to claim 6, further comprising a second quartz ring having a second main surface, the second main surface faces the first region of the quartz ring to form a gap between them,
wherein a difference between the heights of the first region and the second region of the quartz ring is not substantially larger than the gap.

10-25. (Canceled)